

The machines which require minimal training to operate

## Semi-Automatic Wire Bonder Ball , Wedge & Bump



The WB-200-e series are designed as a multi-purposes semiautomatic wire bond tool for R&D purpose, prototype and small series production.

WB-200 provides also a full manual Z Step control for prototyping or simple repair, no mechanical set-up required...

X & Y are motorized for improved bonding accuracy, fine positioning and full loop control,  
Bench Top size with small foot print...

All configurations: Flat Substrates, Deep and Large Packages...

Powerful Video/Focus capability compatible with small bond patterns, and multi-Bond heights application.

Easy bonding into Package Walls or limited Access.

Vibration free design for Improved bond quality,

This is the new generation of JFP wire bonder, with enhanced features, into a robust and reliable mechanical concept.

### SYSTEM

- Table Top machine
- Bond Arm Length: 165mm (6.7")
- Deep-Access bond Head
- Motorized Z Bond Head  
True vertical motion  
Z travel = 40mm,  
Z resolution 0,023µm
- Motorized X & Y : 100x100mm,  
X&Y resolution 0,023µm
- Mouse Motion Drive, pull-drag  
Joystick for x&y cruise
- Ultrasonic power: 0-2 Watt  
Transducer : WBT140 : 62kHz, 185mm Long  
Other Frequency on request
- Motorized up-down Clamp
- Automatic motorized wire Spool: 2"
- Electronic Flame-off  
Missing Ball detection
- Touch screen interface : 7"  
Storage: Unlimited programs  
Programs saveable, PC format
- Temperature Controller integrated

### 3 BONDING MODES

- SEMI-AUTO with Stereozoom microscope
- Full MANUAL Z, with Stereozoom Microscope
- AUTO-BOND Cycle with Vertical Camera  
Multi-Height Focus

### PARAMETERS

- Bond Force I and II programmable: 5-130 cN
- Time I and II programmable: 0-2000 ms
- Power I and II programmable
- Loop: Reverse+Height+Length  
Multi-shape Loop programmable per wire
- Bond: Search Height programmable  
Automatic Bond Height detection
- Tail length programmable
- Wire termination: Table Tear
- Wedge Deep Access 90° wire feeding
- Wire capability:  
Gold wire: 17-50µm  
Aluminium wire: 17-50µm  
Ribbon wire: 40-200µm width (12-25µm Thick)
- Heater Stage HP60-250°C  
T° accuracy +/- 1%,  
Adjustable Height+/-10mm  
Working Height: packages up to 110mm

### OPTIONAL Configuration

- Vertical Camera, No parallax,
- Field of View, FOV, **Compatible for very Fine Pitch**
- Digital crossHair, square or circular pattern
- Light: Led illumination

JFP Microtechnic® is a registered trademark

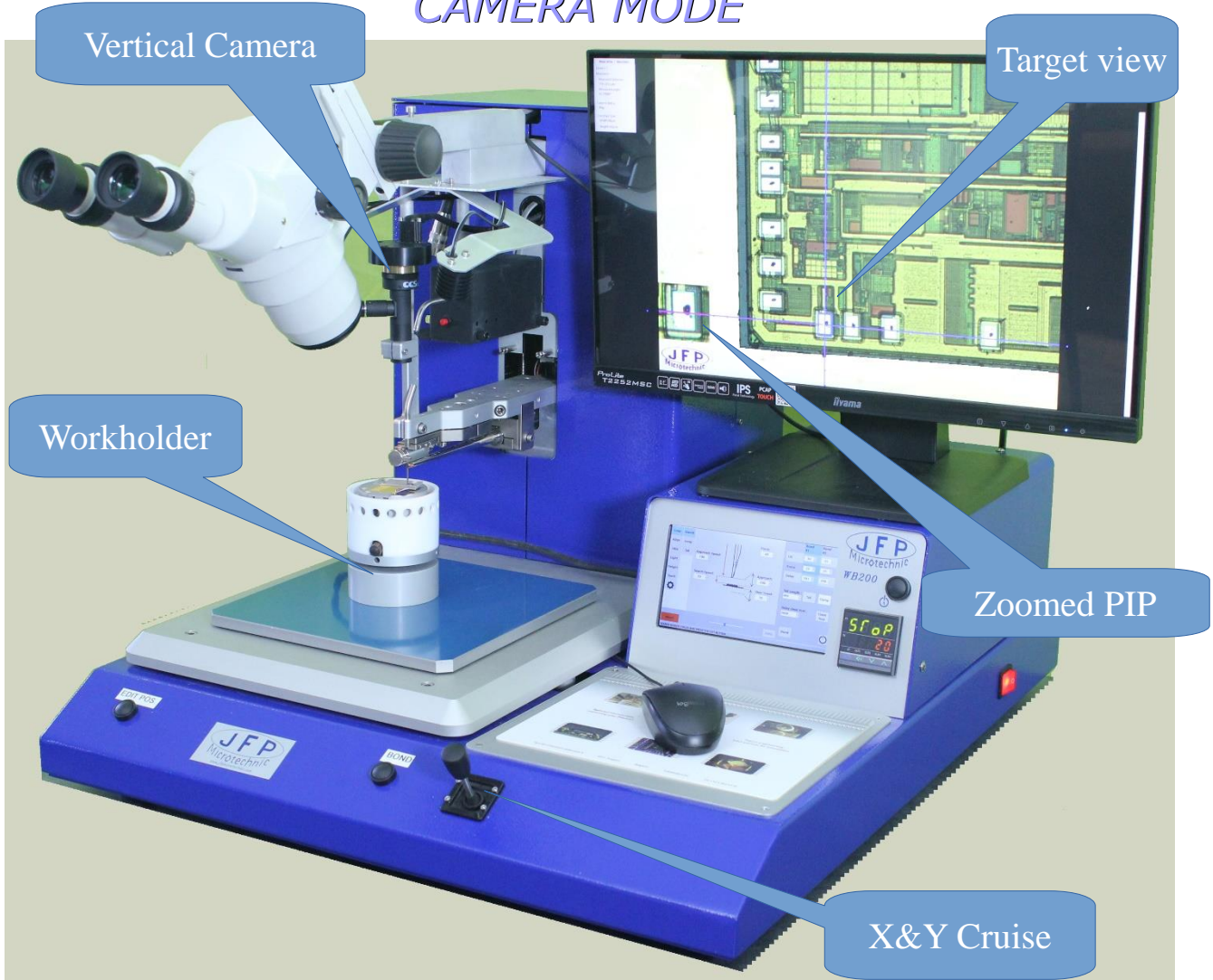
CONTACT / MICROTEST

Tel. +33(4)4 9040 6090 - microtest@microtest-semi.com

www.microtest-semi.com

The machines which require minimal training to operate

## CAMERA MODE



### VERTICAL CAMERA

Operator can directly use the vertical vision to precisely center the bonding pads, with no error. A powerful digital zoom, to easily perform fine pitch applications. A fine focusing capability, to view over 20mm height difference between 1st Bond and 2nd Bond .

### SIDE CAMERA

This option is very useful to check the wire during Bond and Loop, Loop shape and motion can be recorded during bonding, for further analysis. The high definition video format is compatible with UHD TV/Monitors.... Side camera Picture is always at "focus" distance,, no other setup is required (not shown)...

### WB200 BONDING MODES

- Full Manual Z control, with microscope
  - SEMI-AUTO with Stereozoom microscope
  - CAMERA MODE or AUTO-BOND
- Binocular not required to operate

JFP Microtechnic® is a registered trademark

CONTACT / MICROTEST  
Tel. +33(4)4 9040 6090 - [microtest@microtest-semi.com](mailto:microtest@microtest-semi.com)

[www.microtest-semi.com](http://www.microtest-semi.com)

The machines which require minimal training to operate

## VARIOUS

### AUTOMATIC WIRE DESPOOLER

Extra spare to be used as storage and wire identifier purposes



### TAB - Heated Worholder

Chip to lead frame assembly...  
Lead width 40µm  
Frame holder 50x50mm



### OPTIONS

- HP-60 Heated Workholder 60mm diameter
- HP-100 Heated Workholder 100 x100 mm
- HP-150 Heated Workholder 150 x 100 mm
- HP-200 Heated Workholder 200 x 150 mm
- TH-TC Tool Heater with Thermocouple
- More options
- 90° Pivoting work-holder

### TECHNICAL DATA

- Ultrasonic system: PLL, 62kHz
- Power: 0-2 watt
- Bond Time: 15-5000 msec
- Force: 15- 150 cNm
- Capillary tool: 1,58mm (1/16") diameter



HP60



HP-100

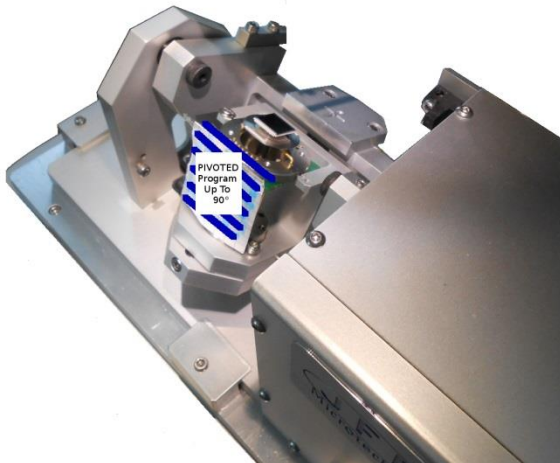


HP-200

Pivoting Workholder

Programmable Angle: 0 °up to 90° Tilt

Compatible for long wires, and deep packages



### TECHNICAL REQUIREMENTS

Power	100 / 240V , 50-60Hz
Current:	max. 5A
Dimensions:	580*510*490 mm (23"x21"x19")
Weight:	45 kg.

JFP Microtechnic® is a registered trademark

CONTACT / MICROTEST

Tel. +33(4)4 9040 6090 - microtest@microtest-semi.com

www.microtest-semi.com